Materials Declaration Form

IPC	**1752**	**Version**	**2**
Form Type *	Distribute		
Sectionals *	Material Info	**Subsectionals ***	A-D
	Manufacturing Info		**** : Required Field***

Supplier Information			
Company Name *	STMicroelectronics	**Response Date ***	13-07-2023
Company Unique ID	NL 008751171B01		
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Contact Phone *	Refer to Supplier Comment section	**Contact Email ***	Refer to Supplier Comment section
Authorized Representative *	Material Declaration champion	**Representative Title**	Material Declaration champion
Representative Phone *	Refer to Supplier Comment section	**Representative Email ***	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement

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Legal Statement

Supplier Acceptance *	true	**Legal Declaration ***	Standard

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as omprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier’s liability and the Company’s remedies for issues that arise regarding information the Supplier provides in this form.

Signature Not
Verified

Digitally signed by
MDF Champion
Date: 2023.07.13
12:03:50 +08:00

Product				
Mfr Item Number	**Mfr Item Name**	**Version**	**Mfr Site**	**Date**
STM32H573IIK3Q	23MR*484XXXX	A	9991	13-07-2023
	Amount	UoM	**Unit type**	**ST ECOPACK Grade**
	111.00	mg	Each	ECOPACK® 2
.	Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant (in each organic material)		

Manufacturing information				
J-STD-020 MSL Rating	**Classification Temp**	**Nbr of Reflow Cycles**		
3	260	3		
bulk Solder Termination	**Terminal Plating**	**Terminal Base Alloy**	**Comment**	
Not Applicable ; if coating is used or other bulk termaination : add in comments	NAC	Copper Alloy	**96.5SN/3.5AG_0.20MM**	

Package Designator	Size	Nbr of instances	Shape	
BGA	10x10	201	bulk solder	
Comment	Package : A0E7 UFBGA 10X10X0.6 176+25 P0.65 8249558			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	**Response**
1 - Product(s) meets EU RoHS requirement without any exemptions	**TRUE**
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE

Exemption Id.	**Description**

QueryList : REACH-10 Jun 2022				
Query				**Response**
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				**true**
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						**Mfr Item Name**	**23MR*484XXXX**				5999999.0	999998.7
Homogeneous Material	**Material Group**	**Mass**	**UoM**	**Level**	**Substance Category**	**Substance**	**CAS**	**Exempt**	**Mass**	**UoM**	**Concentration in homogeneous material (ppm)**	**Concentration in product (ppm)**
Die or dies	M-011 Other inorganic materials	2.027	mg	supplier	die	Silicon (Si)	7440-21-3		1.656	mg	816971	14919
				supplier	metallization	Aluminium (Al)	7429-90-5		0.044	mg	21707	396
				supplier	metallization	Copper (Cu)	7440-50-8		0.138	mg	68081	1243
				supplier	metallization	Nickel (Ni)	7440-02-0		0.001	mg	493	9
				supplier	metallization	Tantalum (Ta)	7440-25-7		0.022	mg	10853	198
				supplier	metallization	Titanium (Ti)	7440-32-6		0.004	mg	1973	36
				supplier	metallization	Tungsten (W)	7440-33-7		0.001	mg	493	9
				supplier	Passivation	Silicon Oxide	7631-86-9		0.161	mg	79428	1450
Substrate (A299420)	M-011 Other inorganic materials	40.183	mg	supplier	BT-substrate	Thermosetting resin (Inorganic filler)	Undisclosed		3.817	mg	95000	34391
				supplier	BT-substrate	Glass cloth	65997-17-3		10.247	mg	255000	92312
				supplier	BT-substrate	Copper foil	7440-50-8		15.470	mg	385000	139373
				supplier	Solder mask	3-methoxy-3-methylbutylacetate	03429-90-9		5.626	mg	140000	50681
				supplier	Solder mask	Morpholinederivative	Trade secret		1.025	mg	25500	9231
				supplier	Solder mask	Barium Sulfate	7727-43-7		0.782	mg	19450	7041
				supplier	Solder mask	Talc containing no as bestiform fibers	14807-96-6		0.826	mg	20550	7439
				supplier	Solder mask	Dipropylene glycol monomethyl ether	34590-94-8		2.391	mg	59500	21540
DAF (ATB-125)	M-011 Other inorganic materials	2.965	mg	supplier	film	Butadiene, acrylonitrile polymer, carboxy-termi	68610-41-3		2.069	mg	697750	18638
				supplier	film	Formaldehyde, polymer with (chloromethyl)ox	37382-79-9		0.862	mg	290750	7766
				supplier	film	[3-(2,3-Epoxypropoxy)propyl]trimethoxysilane	2530-83-8		0.017	mg	5750	154
				supplier	film	Reaction product: bisphenol-A-(epichlorhydrin)	25068-38-6		0.017	mg	5750	154
Bonding wire (CuPd)	Precious metals	1.163	mg	supplier	Bonding wire	Gold (Au)	7440-57-5		0.003	mg	3000	31
				supplier	Bonding wire	Copper (Cu)	7440-50-8		1.136	mg	977000	10236
				supplier	Bonding wire	Palladium (Pd)	7440-05-3		0.023	mg	20000	210
Encapsulation (KE-G1250AAS)	M-011 Other inorganic materials	59.774	mg	supplier	Molding Compound	Epoxy resin	Trade secret		3.347	mg	56000	30156
				supplier	Molding Compound	Silica(Fused)	60676-86-0,7631-86-9		53.797	mg	900000	484654
				supplier	Molding Compound	Phenol resin	Trade secret		2.391	mg	40000	21540
				supplier	Molding Compound	Carbon Black	1333-86-4		0.239	mg	4000	2154
Solderballs (96.5Sn/3.5Ag)	Solder	4.888	mg	supplier	Solder	Tin (Sn)	7440-31-5		4.717	mg	965000	42495
				supplier	Solder	Silver (Ag)	7440-22-4		0.171	mg	35000	1541